# EA3250 Series

COMPLIANT



REGULATORY COMPLIANCE						
Lead Free	EU RoHS	China RoHS	REACH			
P	2011/65 +	e	SVHC			

### ITEM DESCRIPTION

COMPLIANT

Quartz Crystal Resonator 3.2mm x 5.0mm x 1.0mm 4 Pad Ceramic Surface Mount (SMD)

COMPLIANT

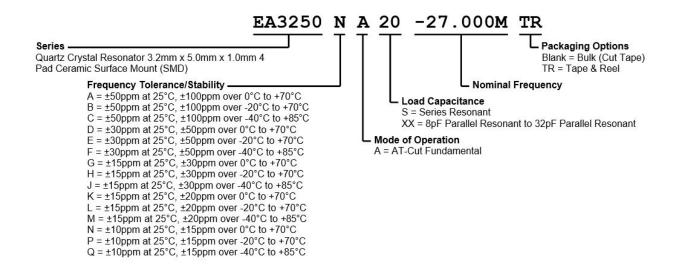
COMPLIANT

# ELECTRICAL SPECIFICATIONS

Nominal Frequency	8MHz to 48MHz
Frequency Tolerance/Stability	
Aging at 25°C	±3ppm/year Maximum
Load Capacitance	Series Resonant, 8pF Parallel Resonant to 32pF Parallel Resonant
Shunt Capacitance	5pF Maximum
Equivalent Series Resistance	120 Ohms Maximum over Nominal Frequency of 8MHz to 9.999999MHz 70 Ohms Maximum over Nominal Frequency of 10MHz to 11.999999MHz 60 Ohms Maximum over Nominal Frequency of 12MHz to 12.999999MHz 55 Ohms Maximum over Nominal Frequency of 13MHz to 15.999999MHz 50 Ohms Maximum over Nominal Frequency of 16MHz to 23.999999MHz 40 Ohms Maximum over Nominal Frequency of 24MHz to 48MHz
Mode of Operation	AT-Cut Fundamental
Drive Level	100µWatts Maximum
Spurious Response	Measured from Fo to Fo +5000ppm -3dB Minimum
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	Measured at 100Vdc 500 Megaohms Minimum

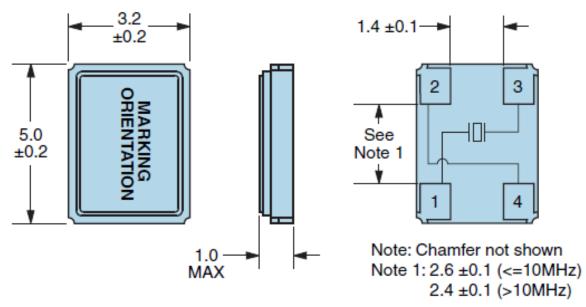


#### PART NUMBERING GUIDE





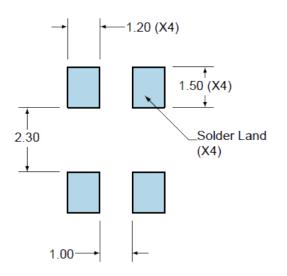
### **MECHANICAL DIMENSIONS**



Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm)

### SUGGESTED SOLDER PAD LAYOUT



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

All Tolerances are ±0.1

## **All Dimensions in Millimeters**

# EA3250 Series

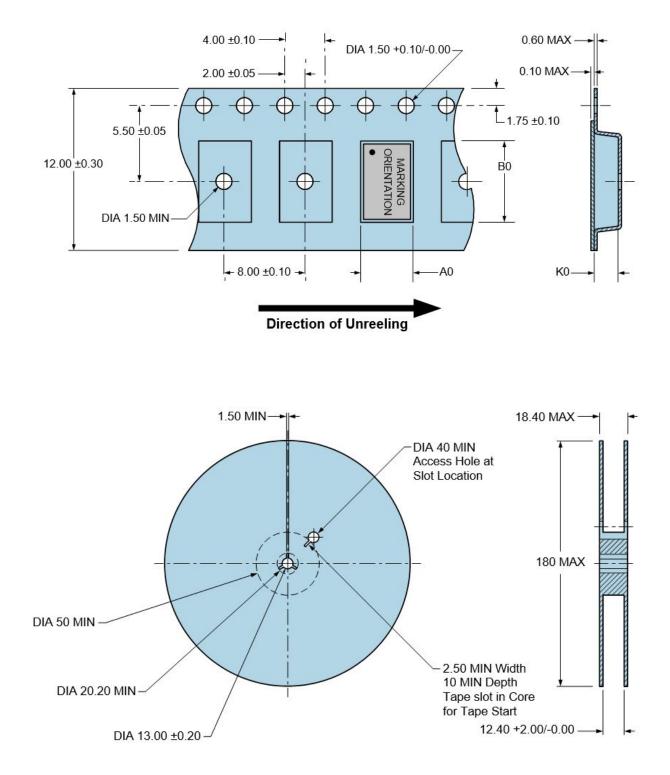


### **TAPE & REEL DIMENSIONS**

Quantity per Reel: 1,000 Units

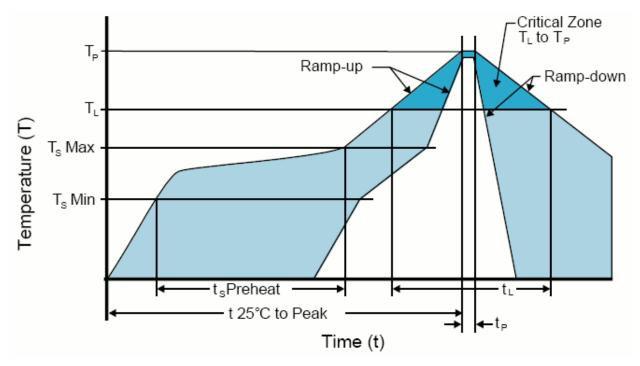
All Dimensions in Millimeters

Compliant to EIA-481





## **RECOMMENDED SOLDER REFLOW METHOD**



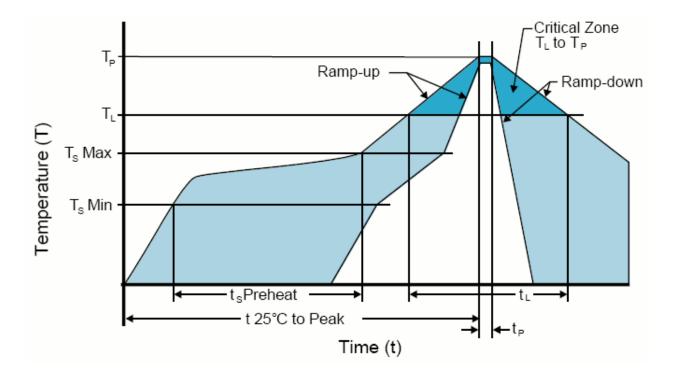
HIGH TEMPERATURE INFRARED/CONVECTION		
$T_s$ MAX to $T_L$ (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (T <sub>s</sub> MIN)	150°C	
- Temperature Typical (T <sub>s</sub> TYP)	175°C	
<ul> <li>Temperature Maximum(T<sub>s</sub> MAX)</li> </ul>	200°C	
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds	
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T <sub>L</sub> )	217°C	
- Time (t∟)	60 - 150 Seconds	
Peak Temperature (T <sub>P</sub> )	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(T <sub>P</sub> Target)	250°C +0/-5°C	
Time within 5°C of actual peak (t <sub>p</sub> )	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

#### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



# **RECOMMENDED SOLDER REFLOW METHOD**



LOW TEMPERATURE INFRARED/CONVECTION		
T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (T <sub>s</sub> MIN)	N/A	
- Temperature Typical (T <sub>s</sub> TYP)	150°C	
<ul> <li>Temperature Maximum(T<sub>s</sub> MAX)</li> </ul>	N/A	
- Time (t <sub>s</sub> MIN)	30 - 60 Seconds	
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T <sub>L</sub> )	150°C	
- Time (t∟)	200 Seconds Maximum	
Peak Temperature (T <sub>P</sub> )	245°C Maximum	
Target Peak Temperature(T <sub>P</sub> Target)	245°C Maximum 2 Times/230°C Maximum 1Time	
Time within 5°C of actual peak (t <sub>P</sub> )	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

#### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)